EPIC-5537WT

Thermal Image Analysis Report

Report NO : 09E080022

Release Date: Sep. 3 , 2009

2009/09/03	*Wenyuan Yang*	*Jerry Tsai*
Issue Stamp	**Manager**	**Test Engineer**

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Thermal Image Analysis

Ⅰ. Model Name: EPIC-5537WT A1.0

Ⅱ. Description: AMD LX + CS5536
EPIC Board

Ⅲ. Date: Sep.03, 2009

Ⅳ. Measure Site: AAEON QE Dept.

Ⅴ. Issued by : Jerry Tsai

Ⅵ.Equipment:
GL200(TH-070)

Ⅶ. Simulation Environment:
- •Temperature: Component Side-1 :25.0℃ , Component Side-2 : 25.0℃
- •CPU : Onboard CPU Geode LX 500MHz
- •RAM : Onboard Memory 256MB
- •BIOS : EPIC-5537WT BIOS Rev 1.0 (03/03/2009)
- •CF Card : N/A
- •HDD : WD WD800JB-00JJC0 80GB 3.5” IDE HDD
- •Application Software: Run Prime95 under Windows XP Professional V2002 Service Pack 3
- •Take Picture Time: After Power on 2 hours.

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Temperature Profile Test:

Component Side-1:

Point	Position	Describe	Tc (℃)	Tm (25.℃)	Tm (60℃)	Note
1	U21	(TF)IC.SMD 208PBGA.I/O Companion.Multi-Function South Bridge.AMD.CS5536AD	110	42.1	77.1	
2	U37	Phase out : 2010/08/01,(TF)IC.SMD PBGA 196P.PCI Ethernet 10/100BaseT.Intel.LU82551ER	85	39.9	74.9	
3	U39	Phase out : 2010/08/01,(TF)IC.SMD PBGA 196P.PCI Ethernet 10/100BaseT.Intel.LU82551ER	85	40.4	75.4	

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4	U46	(TF)IC.SMD.SSOP RS232 Driver ESD 15KV.AD.ADM213EARSZ	85	33.6	68.6	
5	U45	(TF)IC.SMD.SSOP RS232 Driver ESD 15KV.AD.ADM213EARSZ	85	33.8	68.8	
6	U54	(TF)IC.SMD.QSOP 16P.VGA ESD Protection Array.CMD.CM2009-02QR	85	33.6	68.6	
7	U25	(TF)IC.DDR-SDRAM.32M*16(bit).SMDFBGA 60PIN 2.6V.PROMOS.V58C2512164SAJ5	150	34.0	69	
8	U42	(TF)IC.SMD.VTQFP 128P.Super I/O.SMSC.SCH3112-NU	85	39.8	74.8	
9	L1	(TF)COIL.3.3uH.SMD.7.3*6.8*3.0mm.DCR=28m ohm.Irms=6Amp.GOTREND.GSTC063P-3R3MN	125	36.3	71.3	
10	U55	(TF)IC.SMD.2 Channel Audio Codec.Realtek.ALC203-LF	125	46.6	81.6	
11	U20	(TF)AMD CPU.BGU481.LX-800.500MHz.1.25V.AMD.ALXD800EEXJ2VD C3	85	50.2	85.2	
12	U43	(TF)IC.SMD TFBGA.160P.PCI to ISA Bridge Chip.ITE.IT8888G-L	125	45.5	80.5	
13	U50	(TF)IC.SMD.LQFP128P.SATA RAID CONTROLLER.VIA.VT6421A	125	47.8	82.8	
14	L3	(TF)COIL.3.3uH.SMD.7.3*6.8*3.0mm.DCR=28m ohm.Irms=6Amp.GOTREND.GSTC063P-3R3MN	125	50.1	85.1	
15	L2	(TF)COIL.3.3uH.SMD.7.3*6.8*3.0mm.DCR=28m ohm.Irms=6Amp.GOTREND.GSTC063P-3R3MN	125	47.4	82.4	

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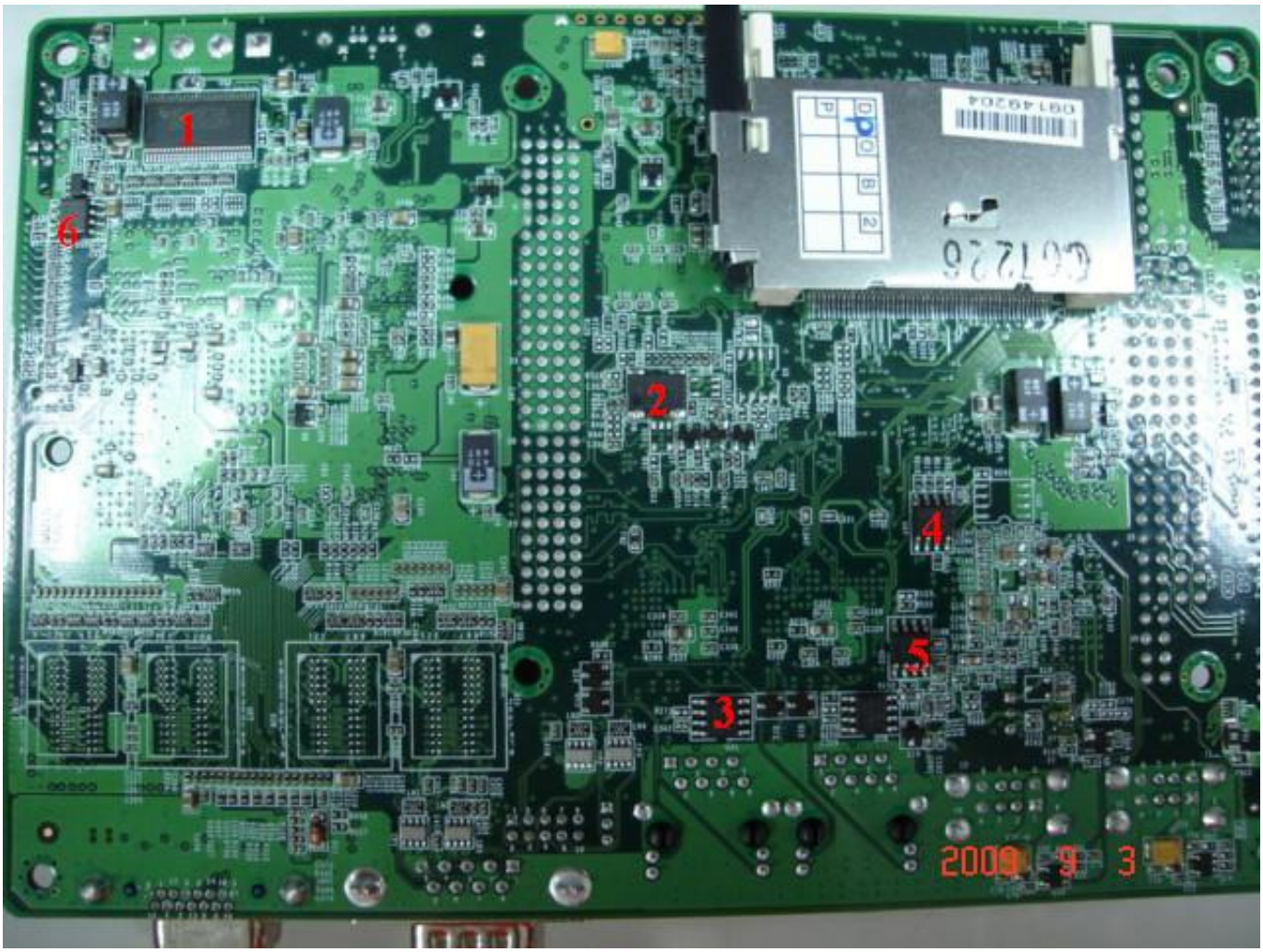
16	U14	(TF)IC.SMD.SSOP28.Clock Generator.ICS.MK1491-09FLN	100	52.3	87.3	
17	Q2	(TF)Dual N-Channel.SO-8.SMD.Vds=30V.Ids=6A.Rds=21/27mohm.Vgs=10/4.5V .ANPEC.APM7313KC-TRL	125	49.9	84.9	

1.Tm (Measured operation temperature) must be less than Tc (Specified case temperature) +5 degree C
2.Any Tm value showed in red words which meaning the value is over the Tc+ 5 degree C of this device specification
3.The Tm value showed in BLUE words which meaning the MEASUREDoperation temperature within (Tc- 10℃)>Tm> (Tc+ 5℃),particular thermal dissipation design is needed if you wanna to utilize this board in an enclosure box or chassis.
4.Any Tm value showed in RED words which meaning the operation temperature is over(Tc+ 5℃).The result is "Failed" and must be solved before the product launched into next design stage.

.Temperature Profile Test:

Component Side-2:



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Point	Position	Describe	Tc (℃)	Tm (25℃)	Tm (60℃)	Note
1	U53	(TF)IC.SMD.TSSOP56.FlatLink Transmitter.TI.SN75LVDS83	125	48.6	83.6	
2	Y8	(TF)OSC.32.768KHz.SMD.7.1*4.6mm.4P.3.3V 5+/-27PPM.ARGO.Epson SG3030JF	125	41.5	76.5	
3	U41	(TF)IC.SMD.SOIC 8P.2.5V 1K bits.Microchip.93LC46B/SN	125	34.7	69.7	
4	U57	(TF)IC.SMD.SOIC-8P.2K Serial EEPROM.ATMEL.AT24C02BN-SH-T	125	37.0	72	
5	U22	(TF)IC.SMD SO-8.5V.Supervisory Circuits.ANALOG DEVICES.ADM705ARZ	115	36.2	71.2	
6	U51	(TF)PWR.SMD SO-8.P-Channel 2.5V(G-S) MOSFET.VISHAY.SI9933BDY-T1-E3	125	41.1	76.1	

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